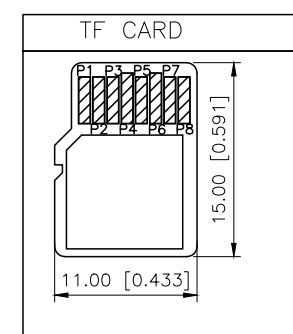
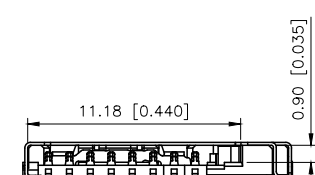
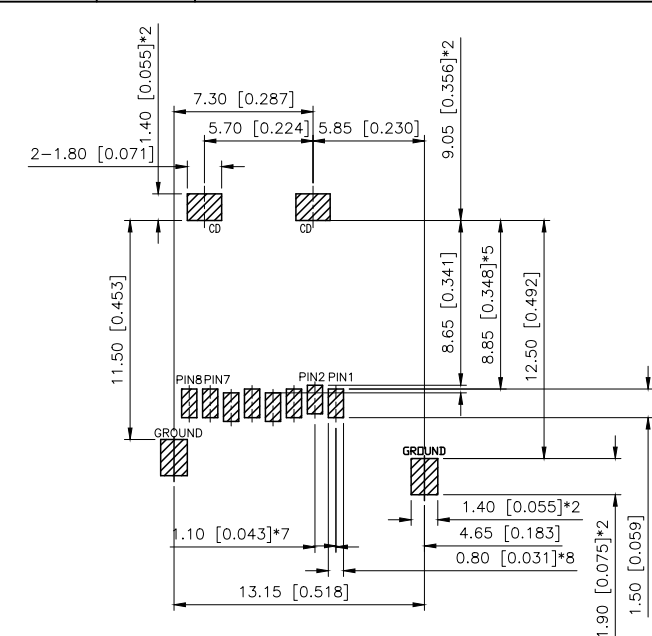
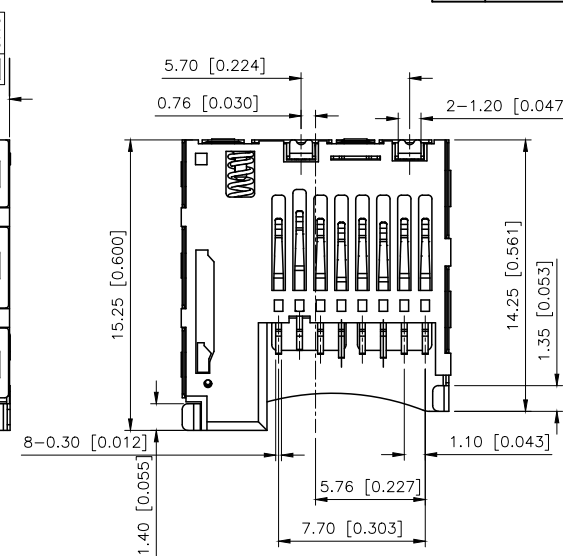
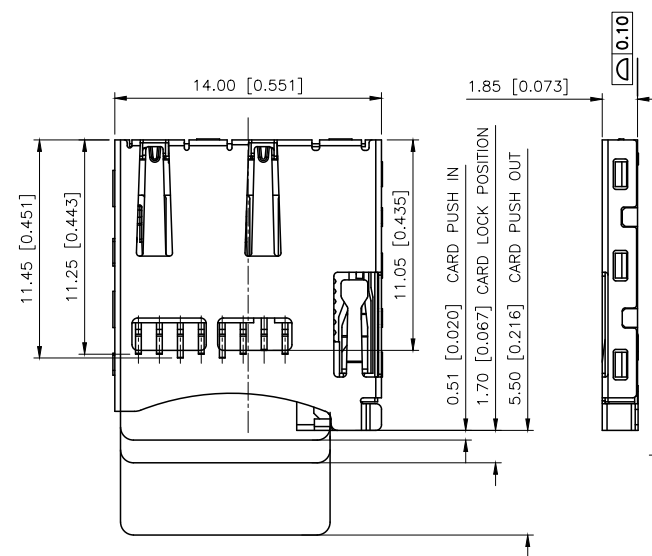
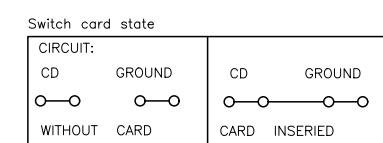


REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.05.16	阿树



- NOTES:
- MATERIAL:
 - Housing:HI-TEMP.PLASIC
UL94V-0; Color Black.
 - Terminal:Copper Alloy.
 - Shell:SUS.
 - PLATING:
 - Contact: Contact Area: Au G/F, Solder area: Matte tin
;Under plate Ni all over
 - SHELL: Solder Area: Au G/F, Under plate Ni all over
 - CD PIN: Contact Area: Au G/F, Under plate all over
 - SPECIALITY:
 - Rated current: 1.0A
 - Rated voltage: 30V
 - Contact Resistance: 50mΩ MAX
 - Insulation Resistance: 1000MΩ MIN 500V DC
 - Dielectric withstanding voltage: 500V AC.
 - Solder ability: 255±5℃, 5±0.5s.
 - Durability: 10000 Cycles Min.
 - Operating condition: Temperature -40℃~+85℃;
Humidity 80% R.H MAX



Pin No.	MICRO SD
PIN1	DAT2 1P
PIN2	CD/DAT3 2P
PIN3	CMD 3P
PIN4	VDD 4P
PIN5	CLK 5P
PIN6	VSS 6P
PIN7	DAT0 7P
PIN8	DAT1 8P
PIN9	CARD DETECT

③	Shell	1	SUS
②	Terminal	10	COPPER ALLOY
①	Housing	1	HI-TEMP,PLASIC UL 94V-0 BLACK
ITEM	PAPT NAMF	QTY	MATERIAL FINISHING

AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERANCES	



DESIGN	阿树	VIEW:	MODEL TYPE: TF CARD CONN
CHECKED		UNIT: mm/in	PART NO.: XKTF-001C
APPROVED		SIZE: A4	DWG NO.: